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TITLE: MANUFACTURE OF WIRING BOARD  
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ABSTRACT:

PURPOSE: To make a high-density wiring using a 0.10mm wire and to obtain a multiwire wiring board which meets a condition  $Z_0$  (impedance)=50ohms and has an excellent insulation deteriorating property, by covering a recessed portion of an insulating board, on which an inner circuit is formed, with material which is made by mixing several kinds of resins in specific proportions.

CONSTITUTION: A gland circuit 3 is formed as a power supply on an insulating board 2. A compound of 10 $\sim$ 50 pts.wt. epoxy resin whose molecular weight is

5,000 or more, 5±25 pts.wt. alkylmelamine resin, 5±50 pts.wt. saturated polyester and 10±40 pts.wt. inorganic fiber filler as against 100 pts.wt. epoxy resin whose molecular weight is less than 5,000 and a crosslinking agent are dissolved in a mixed solvent, dispersed, coated on a separation film and cured to a state of **B stage**. This is placed on an inner circuit board 1 and is applied with pressure and heat with an end plate piled on it, to form a resin layer 4 with a smooth surface. Next, an adhesive resin layer 5 is laminated, on the surface of which, a wire 6 is adhered to a desired wiring pattern. Then, a thermosetting resin layer 7 is formed and a hole is made. On an inner surface of the hole, a through-hole copper-plated layer 8 is formed.

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